

L Number	Hits	Search Text	DB	Time stamp
2	14563	(wiring near (layer film)) with (hole via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/31 09:46
3	192893	gate and source and drain	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/31 09:46
4	2869	((wiring near (layer film)) with (hole via)) and (gate and source and drain)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/31 09:47
5	503477	(insulat\$3 dielectric) near (layer film)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/31 09:47
6	2643	((wiring near (layer film)) with (hole via)) and (gate and source and drain)) and ((insulat\$3 dielectric) near (layer film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/31 09:48
7	2588	((wiring near (layer film)) with (hole via)) and (gate and source and drain)) and ((insulat\$3 dielectric) near (layer film)) and (substrate wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/31 09:49